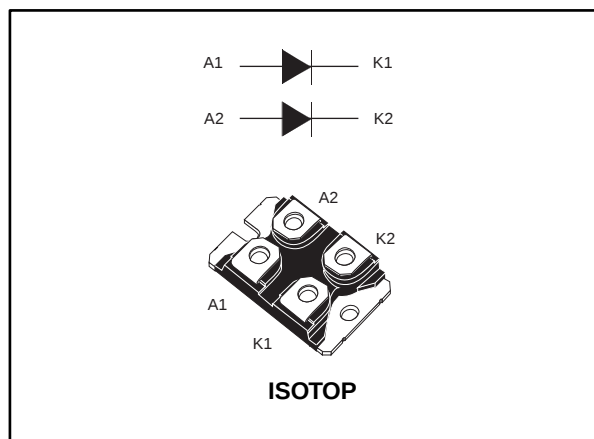


High voltage power Schottky rectifier

Datasheet - production data



Description

High frequency dual Schottky rectifier designed for high frequency telecom, computer SMPS and other power converters.

Packaged in ISOTOP, this device is intended for use in medium voltage operation and in high frequency circuitries where low switching losses and low noise are required.

Table 1: Device summary

Symbol	Value
$I_{F(AV)}$	2 x 80 A
V_{RRM}	100 V
T_j (max.)	150 °C
V_F (max.)	0.68 V

Features

- Negligible switching losses
- High junction temperature capability
- Low leakage current
- Good trade-off between leakage current and forward voltage drop
- Avalanche rated
- Low induction package
- Insulated package ISOTOP:
 - Insulated voltage: 2500 V_{RMS}
 - Capacitance: 45 pF



TM: ISOTOP is a trademark of STMicroelectronics

1 Characteristics

Table 2: Absolute ratings (limiting values, per diode)

Symbol	Parameter			Value	Unit
V _{RRM}	Repetitive peak reverse voltage			100	V
I _{F(RMS)}	Forward rms current			180	A
I _{F(AV)}	Average forward current, δ = 0.5	T _C = 110 °C	Per diode Per device	80 160	A
I _{FSM}	Surge non repetitive forward current	t _p = 10 ms sinusoidal		1000	A
I _{RRM}	Repetitive peak reverse current	t _p = 2 μs square f = 1 kHz		2	A
I _{RSM}	Non repetitive peak reverse current	t _p = 100 μs square		10	A
P _{ARM}	Repetitive peak avalanche power	t _p = 10 μs T _j = 125 °C		5400	W
T _{stg}	Storage temperature range			-55 to +150	°C
T _j	Maximum operating junction temperature ⁽¹⁾			150	°C

Notes:

⁽¹⁾ $(dP_{tot}/dT_j) < (1/R_{th(j-a)})$ condition to avoid thermal runaway for a diode on its own heatsink.

Table 3: Thermal parameters

Symbol	Parameter		Maximum values	Unit
$R_{th(j-c)}$	Junction to case	Per diode	0.9	$^{\circ}\text{C/W}$
		Total	0.5	
$R_{th(c)}$	Coupling		0.14	

When the diodes 1 and 2 are used simultaneously:

$$\Delta T_j (\text{diode1}) = P_{(\text{diode1})} \times R_{th(j-c)} (\text{per diode}) + P_{(\text{diode2})} \times R_{th(c)}$$

Table 4: Static electrical characteristics

Symbol	Parameter	Test conditions		Min.	Typ.	Max.	Unit
$I_R^{(1)}$	Reverse leakage current	$T_J = 25\text{ }^{\circ}\text{C}$	$V_R = V_{RRM}$	-		40	μA
		$T_J = 125\text{ }^{\circ}\text{C}$		-	13	50	mA
$V_F^{(2)}$	Forward voltage drop	$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 60\text{ A}$	-		0.75	V
		$T_J = 125\text{ }^{\circ}\text{C}$		-	0.59	0.63	
		$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 80\text{ A}$	-		0.80	
		$T_J = 125\text{ }^{\circ}\text{C}$		-	0.63	0.68	
		$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 120\text{ A}$	-		0.87	
		$T_J = 125\text{ }^{\circ}\text{C}$		-	0.69	0.74	
		$T_J = 25\text{ }^{\circ}\text{C}$	$I_F = 160\text{ A}$	-		0.92	
		$T_J = 125\text{ }^{\circ}\text{C}$		-	0.75	0.80	

Notes:

⁽¹⁾Pulse test: $t_p = 5\text{ ms}$, $\delta < 2\%$

⁽²⁾Pulse test: $t_p = 380\text{ }\mu\text{s}$, $\delta < 2\%$

To evaluate the maximum conduction losses, use the following equation:

$$P = 0.56 \times I_{F(AV)} + 0.0015 \times I_{F(RMS)}^2$$

1.1 Characteristics (curves)

Figure 1: Conduction losses versus average forward current (per diode)

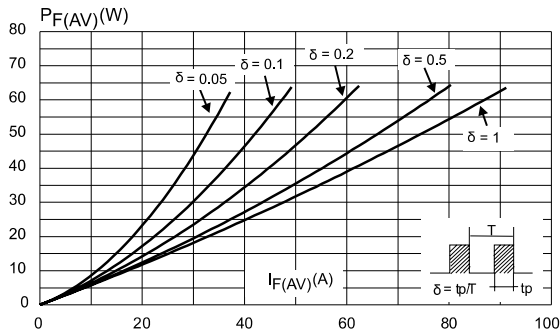


Figure 2: Forward voltage drop versus forward current ($\delta = 0.5$, per diode)

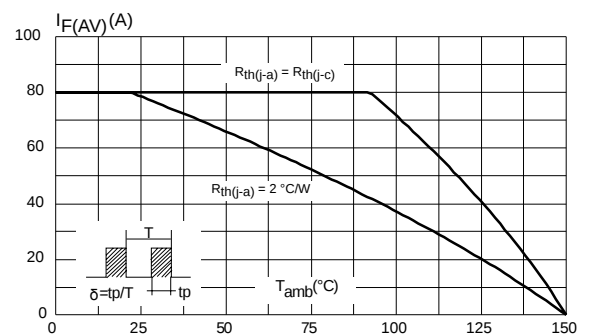


Figure 3: Normalized avalanche power derating versus pulse duration

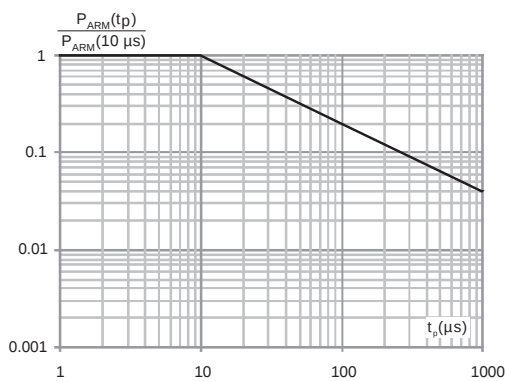


Figure 4: Relative variation of thermal impedance junction versus pulse duration (per diode)

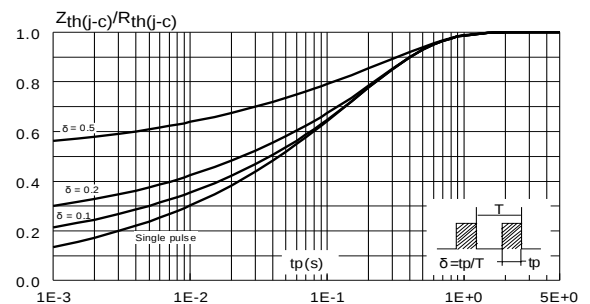


Figure 5: Reverse leakage current versus reverse voltage applied (typical values, per diode)

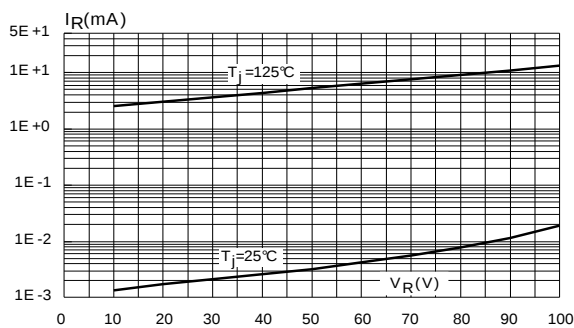


Figure 6: Junction capacitance versus reverse voltage applied (typical values, per diode)

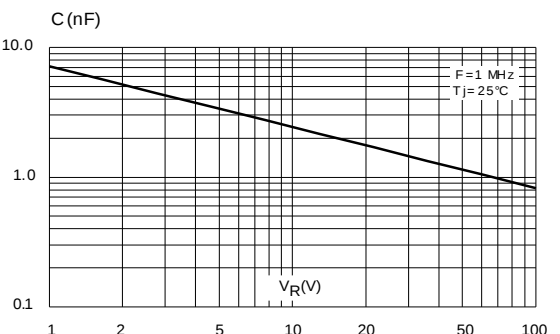
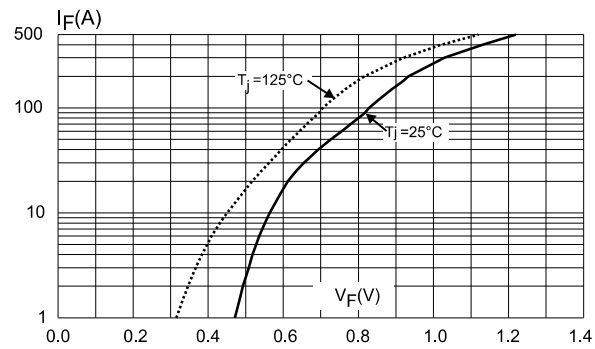


Figure 7: Forward voltage drop versus forward current (maximum values, per diode)



2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque value: 1.3 N·m
- Maximum torque value: 1.5 N·m

STMicroelectronics strongly recommends the use of the screws delivered with this product.

The use of any other screws is entirely at the user's own risk and will invalidate the warranty.

2.1 ISOTOP package information

Figure 8: ISOTOP package outline

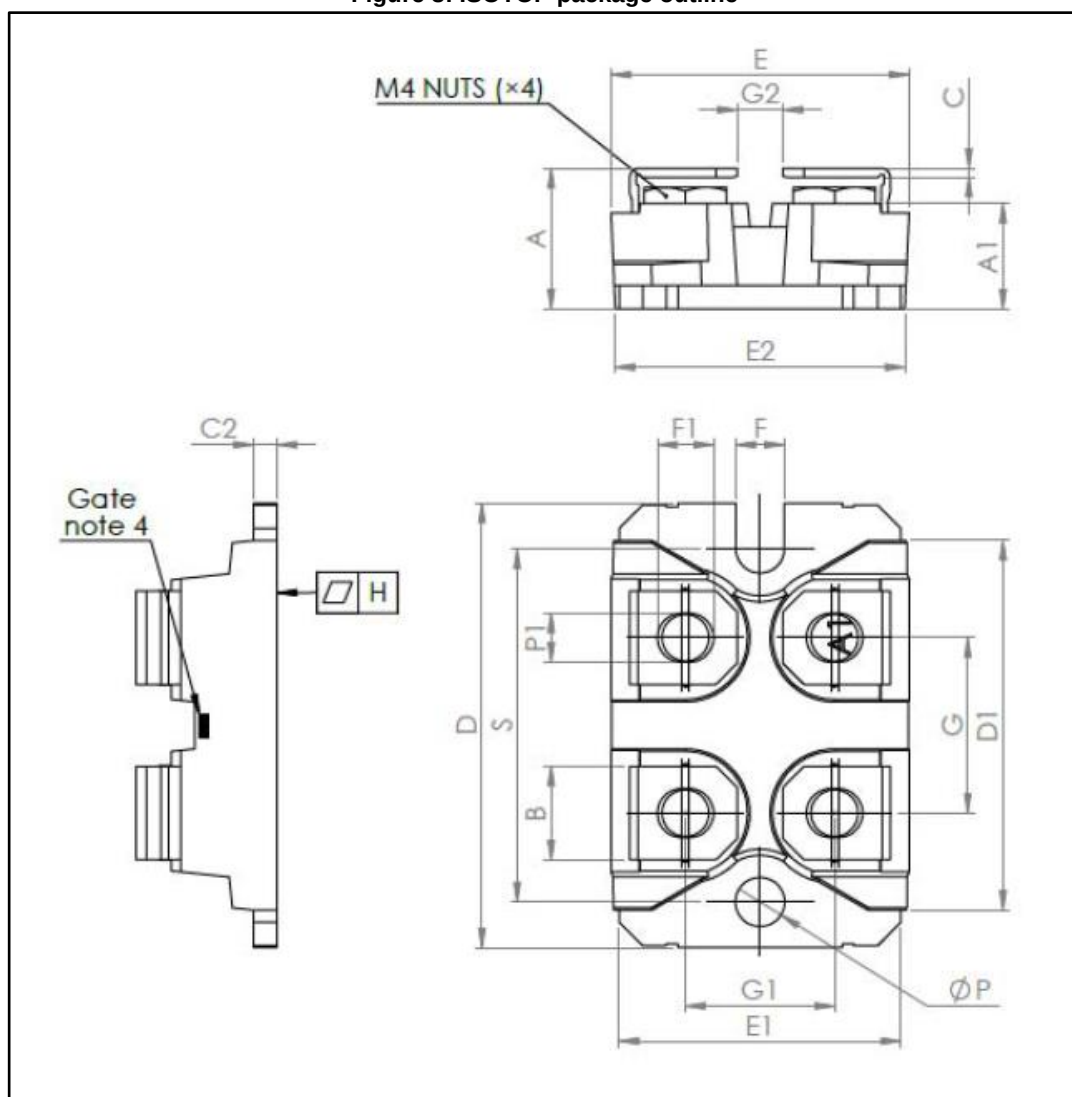


Table 5: ISOTOP package mechanical data

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	11.80	12.20	0.460	0.480
A1	8.90	9.10	0.350	0.358
B	7.80	8.20	0.307	0.323
C	0.75	0.85	0.030	0.033
C2	1.95	2.05	0.077	0.081
D	37.80	38.20	1.488	1.504
D1	31.50	31.70	1.240	1.248
E	25.15	25.50	0.990	1.004
E1	23.85	24.15	0.939	0.951
E2	24.80		0.976	
G	14.90	15.10	0.587	0.594
G1	12.60	12.80	0.496	0.504
G2	3.50	4.30	0.138	0.169
F	4.10	4.30	0.161	0.169
F1	4.60	5	0.181	0.197
H	-0.05	0.1	-0.002	0.004
Diam P	4	4.30	0.157	0.169
P1	4	4.40	0.157	0.173
S	30.10	30.30	1.185	1.193

3 Ordering information

Table 6: Ordering information

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS160H100TV	STPS160H100TV	ISOTOP	27 g (without screws)	10 (with screws)	Tube

4 Revision history

Table 7: Document revision history

Date	Revision	Changes
Jul-2003	3a	Last release.
06-Jun-2017	4	Updated Section 2.1: "ISOTOP package information" .
24-Nov-2017	5	Updated Table 5: "ISOTOP package mechanical data" .

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